



MULTILAYER CERAMIC CAPACITORS Ultra-small Series (6.3V to 50V) 0201 Size NP0, X7R, X5R Dielectrics RoHS Compliance

*Contents in this sheet are subject to change without prior notice.



1. INTRODUCTION

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

0201 MLCC is performed by high precision technology achieve high capacitance in unit size and ensure the stability and reliability of products.

2. FEATURES

- b. High capacitance in unit size.
- c. High precision dimensional tolerances.
- d. Suitable used in high-accuracy automatic mounting machine.

3. APPLICATIONS

- a. Miniature microwave module.
- b. Portable equipments (ex. Mobile phone, PDA).
- c. High frequency circuits.

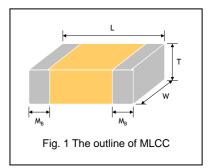
4. HOW TO ORDER

<u>0201</u>	B	<u>102</u>	<u>K</u>	<u>250</u>	<u>C</u>	I
Size	Dielectric	Capacitance	Tolerance	Rated voltage	Termination	Packaging
Inch (mm) 0201 (0603)	N =NP0 (C0G) B =X7R	And R is in place of	B =±0.1pF C =±0.25pF D =±0.5pF	Two significant digits followed by no. of zeros. And R is in	L=Ag/Ni/Sn (for NP0 dielectric) C=Cu/Ni/Sn (for X7R,	T=7" reeled
	X =X5R	decimal point. eg.:	F=±1% G=±2% J=±5%	place of decimal point. 6R3=6.3 VDC	X5R dielectric)	
		0R5=0.5pF 1R0=1.0pF 102=10x10 ²	K=±10% M=±20% Z=-20/+80%	100=10 VDC 160=16 VDC 250=25 VDC		
		=1000pF		500=50 VDC		



5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Symbol M		М _в (mm)
0201 (0603)	0.60±0.03	0.30±0.03	0.30±0.03	L	0.15±0.05
* Reflow soldering	g only.				



6. GENERAL ELECTRICAL DATA

Size		0201		
Dielectric	NP0	X7R	X5R	
Capacitance*	0.3pF to 100pF	100pF to 10nF	100pF to 0.47µF	
	Cap≤5pF: B (±0.1pF), C (±0.25pF)			
Capacitance tolerance**	5pF <cap<10pf: (±0.25pf),d(±0.5pf)<br="" c="">Cap≥10pF: F (±1%), G (±2%), J (±5%),</cap<10pf:>	J (±5%), K (±10%), M (±20%)	J (±5%),K (±10%), M (±20%)	
	K (±10%)			
Rated voltage (WVDC)	16V, 25V, 50V	6.3V, 10V, 16V, 25V, 50V	6.3V, 10V, 16V, 25V, 50V	
Tem Σ / Ot	Cap<30pF, Q≥400+20C	Note 1		
Tan δ / Q*	Cap≥30pF, Q≥1000			
Insulation resistance at Ur	≥10GΩ	≥10GΩ or RxC≥500ΩxF whichever is less		
Operating temperature	-55 to +125	C	-55 to +85℃	
Capacitance change	±30ppm	±1	5%	
Termination		Ni/Sn (lead-free termination)		

* Measured at 30~70% related humidity.

NP0: Apply 1.0±0.2Vrms, 1.0MHz±10% at the condition of 25°C ambient temperature.

X7R, X5R: Apply 1.0±0.2Vrms, 1.0kHz±10%(0201/6.3V,Cap≥224 : 0.5±0.2Vrms, 1.0kHz±10%) at the condition of 25℃ ambient temperature.

** Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in a mbient condition for 24±2 hours before measurement.

Note 1:

X7R/X5R

Rated vol.	D.F.	Exception of D.F.			
≥50V	≤3%				
25V	≤3.5%	≤5%	0201≥0.01uF		
16V	≤3.5%	≤5%	0201≥0.01uF		
10V	≤5%	≤10%	0201≥0.012uF		
100	≥3%	≤15%	0201≥0.1uF		
6.3V	≤10%	≤15%	0201≥0.1uF		



7. CAPACITANCE RANGE

SIZE			0201	
	DIELECTRIC		NP0	
RAT	ED VOLTAGE (VDC)	16	25	50
	0.3pF (0R3)		L^	L^
	0.4pF (0R4)		L^	L^
	0.5pF (0R5)		L^	L^
	1.0pF (1R0)		L^	L^
	1.2pF (1R2)		L^	L^
	1.5pF (1R5)		L^	L^
	1.8pF (1R8)		L^	L^
	2.2pF (2R2)		L^	L^
	2.7pF (2R7)		L^	L^
	3.0pF (3R0)		L^	L^
	3.3pF (3R3)		L^	L^
	3.9pF (3R9)		L^	L^
	4.0pF(4R0)		L^	L^
JCe	4.7pF (4R7)		L^	L^
itaı	5.6pF (5R6)		L^	L^
Capacitance	6.8pF (6R8)		L^	L^
Cal	8.2pF (8R2)		L^	L^
	10pF (100)		L^	L^
	12pF (120)		L^	L^
	15pF (150)		L^	L^
	18pF (180)		L^	L^
	22pF (220)		L^	L^
	27pF (270)		L^	L^
	33pF (330)		L^	L^
	39pF (390)		L^	L^
	47pF (470)		L^	L^
	56pF (560)	L^	L^	
	68pF (680)	L^	L^	
	82pF (820)	L^	L^	
	100pF (101)	L^	L^	

	SIZE	0201									
DIELECTRIC		X7R				X5R					
R	ATED VOLTAGE	6.3	10	16	25	50	6.3	10	16	25	50
	100pF (101)			L	L	L			L	L	L
	120pF (121)			L	L	L			L	L	L
	150pF (151)			L	L	L			L	L	L
	180pF (181)			L	L	L			L	L	L
	220pF (221)			L	L	L			L	L	L
	270pF (271)			L	L	L			L	L	L
	330pF (331)			L	L	L			L	L	L
	390pF (391)			L	L	L			L	L	L
	470pF (471)			L	L	L			L	L	L
	560pF (561)			L	L	L			L	L	L
	680pF (681)			L	L	L			L	L	L
	820pF (821)			L	L	L			L	L	L
e	1,000pF (102)	L	L	L	L	L		L	L	L	L
Capacitance	1,500pF (152)	L	L	L				L	L		
acit	2,200pF (222)	L	L	L				L	L		
ap	3,300pF (332)	L	L	L				L	L		
0	4,700pF (472)	L	L	L				L	L		
	6,800pF (682)	L	L					L			
	8,200pF (822)	L	L					L			
	0.010µF (103)	L	L	L			L	L			
	0.015µF (153)						L	L			
	0.022µF (223)						L	L			
	0.033µF (333)						L	L			
	0.047µF (473)						L	L			
	0.068µF (683)						L	L			
	0.082µF (823)						L	L			
	0.10µF (104)						L	L			
	0.22µF (224)						L				
	0.47µF (474)						L				

1. The letter in cell is expressed the symbol of product thickness.

2. The letter in cell with "^" mark is expressed product with Ag/Ni/Sn terminations.

8. PACKAGING DIMENSION AND QUANTITY

Size	Thickness (mm)/Sum	abol	Paper tape		
Size	Thickness (mm)/Syn	7" reel 13" reel		13" reel	
0201 (0603)	0.30±0.03	L	15K	70k	

Unit: pieces

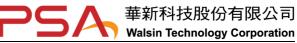


9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	ltem	Test Condition			Requirements				
1.	Visual and Mechanical				* No remarkable defect. * Dimensions to conform to individual specification sheet.			vidual specification sheet.	
2.	Capacitance	Class I: NP0			* Shall not exceed the limits given in the detailed spec.				
3.	Q/ D.F. (Dissipation	Cap>1000pF	ap≤1000pF, 1.0±0.2Vrms, 1MHz±10% ap>1000pF, 1.0±0.2Vrms, 1KHz±10%			30pF, Q≥	1000; Ca	p<30pF, Q≥400+20C	
	Factor)	Class II: X7R			Rated vol.	D.F.	Exception	on of D.F.	
		-	s, 1kHz±10%**	(6.2)()	≥50V	≤3%			
		0.5±0.2VII	ns, 1.0kHz±10% : 0201 ≥0.22 uF	(0.37)	25V	≤3.5%	≤5%	0201≥0.01uF	
					16V	≤3.5%	≤5%	0201≥0.01uF	
					10V	≤5%	≤10%	0201≥0.012uF	
					100	<u> </u>	≤15%	0201≥0.1uF	
					6.3V	≤10%	≤15%	0201≥0.1uF	
4a.	Dielectric Strength	* Duration: 1	ltage (≤100V) 250%. to 5 sec. discharge current less than 50m.	A.	* No evidenc	e of dama	ige or flas	sh over during test.	
5.	Insulation	To apply rate	d voltage for max. 120 sec.		≥10GΩ or Rx	C≥500Ω-	F whiche	ver is smaller.	
	Resistance		C C		Class II (X5R, X6S, X7R, Y5V)				
					Rated volta	ige	Inst	ulation resistance	
					6.3V; 10V:0)201≥47n	F ≥10	00 Ω-F	
6.	Temperature	With no elect	rical load.						
	Coefficient	T.C.	Operating Temp		T.C.	Capacita	nce Cha	nge	
		NP0 (C0G)	-55~125℃ at 25℃		NP0 (C0G)	-	30ppm/℃	:	
		X7R	-55~125℃ at 25℃	_	X7R	Within ±			
		X5R	-55~85℃ at 25℃		X5R	Within ±	15%		
	Adhesive Strength of Termination	* Pressurizing * Test time: 1			* No remarka	ble dama	ge or rem	noval of the terminations.	
8.	Vibration	* Vibration fre	equency: 10~55 Hz/min.		* No remarka	able dama	ige.		
	Resistance	* Total amplit	ude: 1.5mm		* Cap change	e and Q/D	.F.: To m	eet initial spec.	
			hrs. (Two hrs each in three mutu	ally					
		perpendicula	,						
		* Measureme 24±2 hrs.	ent to be made after keeping at ro	om temp. for					
9.	Solderability		perature: 235±5℃		95% min. cov	verage of	all metali	zed area.	
		* Dipping tim	e: 2±0.5 sec.						
10.	Bending Test		part of substrate shall be pressur	-	* No remarka		ige.		
		· · · ·	rizing rod at a rate of about 1 mm				0 F F		
			becomes 1 mm and then the pre	essure shall be				vhichever is larger.	
		maintained for	or 5±1 sec. ent to be made after keeping at ro	om temp for	X7R, X5R: v Y5V: within				
		24±2 hrs.	and to be made and recepting at 10				nge mear	ns the change of capacitance under	
							-	om the capacitance measured before	
					the test.)				



* Cap change:			
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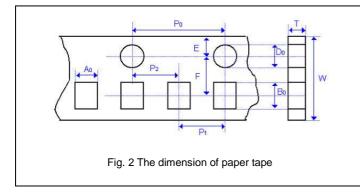


No.	Item	Test Condition	Requirements
14.	Humidity Load (Damp Heat)	 * Test temp.: 40±2°C * Humidity: 90~95%RH * Test time: 500+24/-0 hrs. * To apply voltage : rated voltage. * Before initial measurement (Class II only): To apply test voltage for 1hr at 40°C and then set for 24±2 hrs a t room temp. * Measurement to be made after keeping at room temp. for 24±2 hrs. 	 * No remarkable damage. * Cap change: NP0: within ±7.5% or ±0.75pF whichever is larger. X7R, X5R: ≥10V, within ±12.5%, 10V≥0.1µF, within ±25%; 6.3V, within ±25% Y5V: ≥10V, within ±30% 6.3V, within ±30/-40% * Q/D.F. value: NP0: Cap≥30pF, Q≥200; Cap<30pF, Q≥100+10/3C X7R, X5R: Rated vol. D.F. Exception of D.F. ≥50V ≤6% 25V ≤5% ≤10% 0201≥0.01uF 16V ≤5% ≤15% 0201≥0.01uF 10V ≤7.5% ≤15% 0201≥0.01uF 6.3V ≤15% ≤30% 0201≥0.1uF 6.3V ≤15% ≤30% 0201≥0.1uF * LR.: ≥10V,500MΩ or RxC≥25Ω-F whichever is smaller.
15.	High Temperature Load (Endurance)	 * Test temp.: NP0, X7R: 125±3℃ X5R,Y5V: 85±3℃ * To apply voltage: (1) Cap.≥0.1uF : 100% of rated voltage (2) 6.3V: 150% of rated voltage. (3) >6.3V: 200% of rated voltage. * Test time: 1000+24/-0 hrs. *Before initial measurement (Class II only): To apply test voltage for 1hr at test temp. and then set for 24±2 hrs at room temp. *Measurement to be made after keeping at room temp. for 24±2 hrs 	6.3V; 10V:0201≥47nF, RxC≥5Ω-F * No remarkable damage. * Cap change: NP0: within ±3.0% or ±0.3pF whichever is larger. X7R, X5R: ≥10V, within ±12.5%, 10V ≥ 0.1µF, within ±25%; 6.3V, within ±25% Y5V: ≥10V, within ±30% 6.3V, 200+F X7R, X5R: Rated vol. D.F. 250V ≤6% 25V ≤5% 25V ≤5% 25V ≤5% 25V ≤5% 25V ≤5% 25V ≤5% 25% ≤15% 200 0201≥0.01 uF 10V ≤7.5% 20% ≥16Ω or RxC≥50Ω-F whic

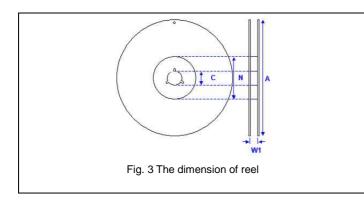


10. APPENDIXES

■ Tape & reel dimensions

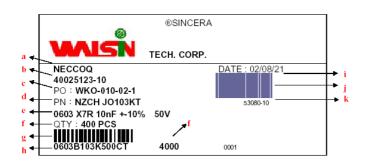


Size	0201
Thickness	L
A ₀	0.38±0.05
Bo	0.68±0.05
Т	0.42±0.05
Ko	-
W	8.00±0.10
Po	4.00±0.10
10xP₀	40.0±0.10
P 1	2.00±0.05
P ₂	2.00±0.05
Do	1.55±0.05
D ₁	-
E	1.75±0.05
F	3.50±0.05

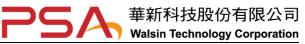


Size	020	01
Reel size	7"	13"
С	13.0+0.5/-0.2	13.0+0.5/-0.2
W ₁	8.4+1.5/-0	8.4+1.5/-0
Α	178.0±0.10	330.0±1.0
N	60.0+1.0/-0	100±1.0

Description of customer label

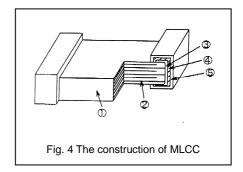


- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer
- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
- k. Serial number of label



Constructions

No.	Name		NP0	X7R, X5R
1	Ceramic material		BaTiO₃ based	
2	Inner electrode		AgPd alloy	Ni
3		Inner layer	Ag	Cu
4	Termination	Middle layer	Ni	
5		Outer layer	Sn (Matt)	



Storage and handling conditions

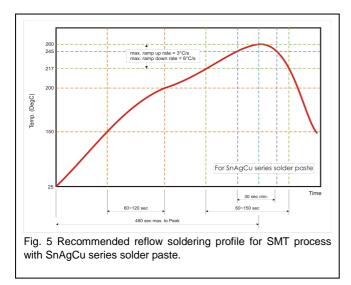
- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

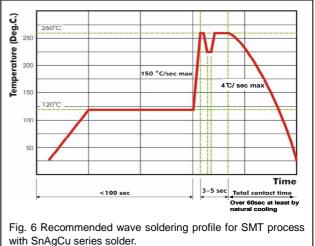
Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N₂ within oven are recommended.





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